

BEST AVAILABLE COPY

Fax:23698454

Jul 13 '05 17:22 P. 08/08

Customer No.: 31561
Application No.: 10/707,015
Docket NO.: 10542-US-PA

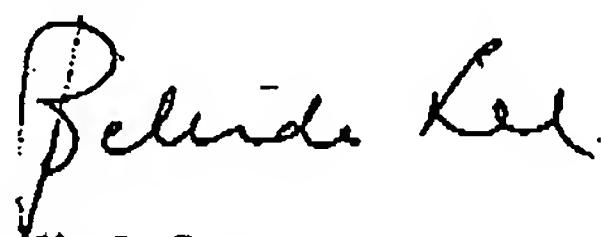
REMARKS

In response to the Office Action, mailed June 15, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-10, drawn to a process for fabricating a substrate, classified in class 29, subclass 830+. Please cancel Group II, claims 11-14, drawn to a substrate, classified in class 174, subclass 255, without waiver, prejudice or disclaimer.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date : July 13, 2005



Belinda Lee

Registration No.: 46,863

Jianq Chyun Intellectual Property Office
7th Floor-1, No. 100
Roosevelt Road, Section 2
Taipei, 100
Taiwan
Tel: 011-886-2-2369-2800
Fax: 011-886-2-2369-7233
Email: belinda@jcipgroup.com.tw
Usa@jcipgroup.com.tw